



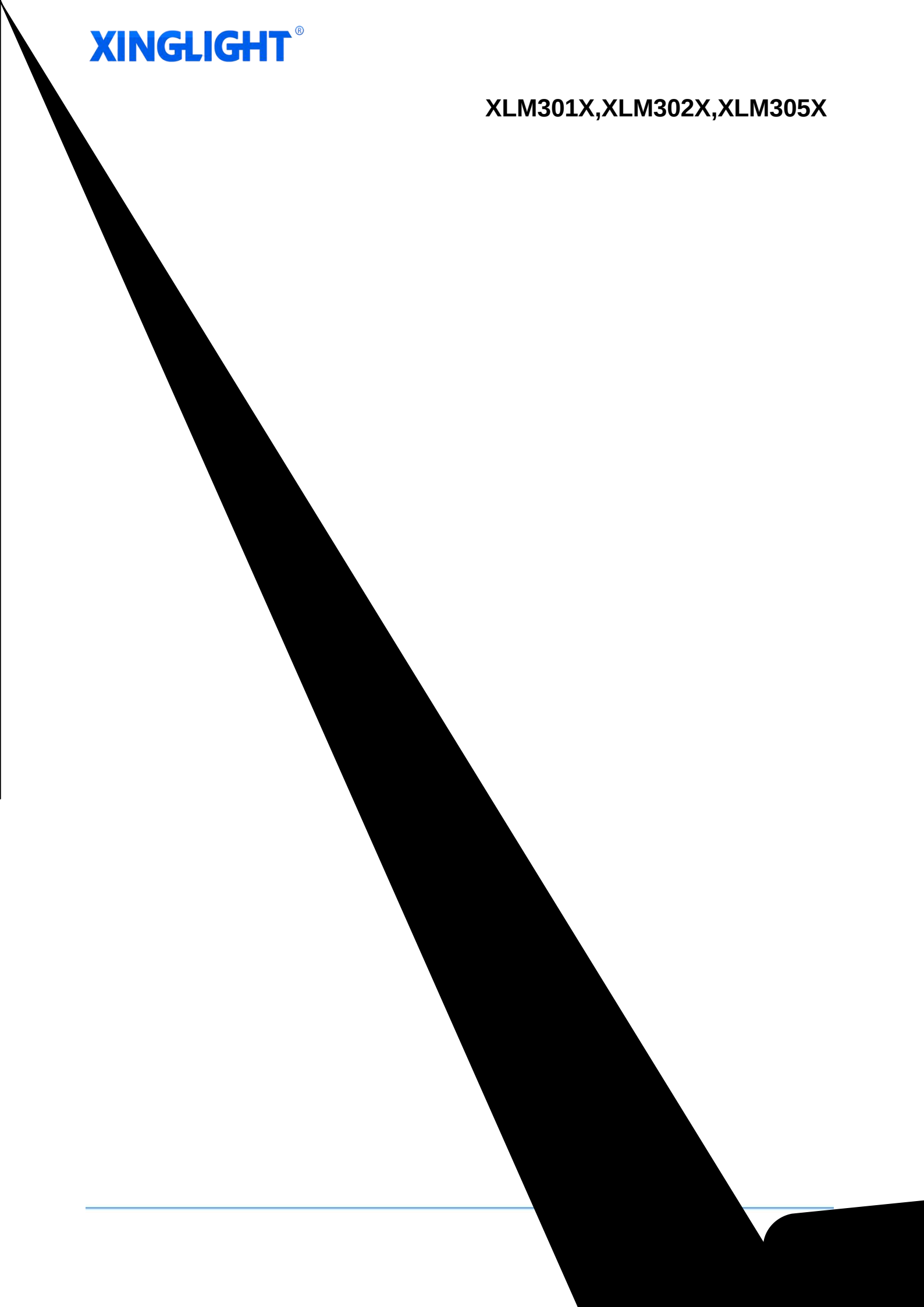
IB **NGHICHT®**

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XLM301X,XLM302X,XLM305X





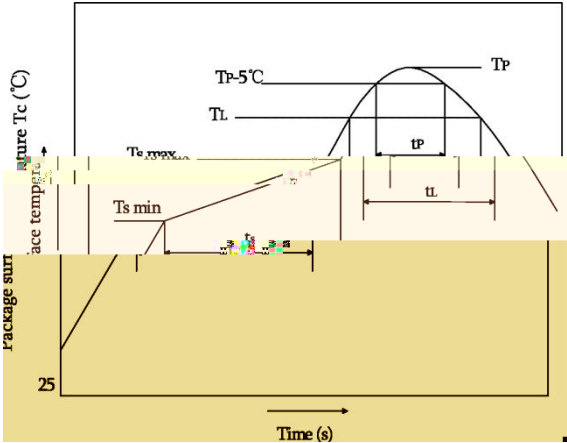








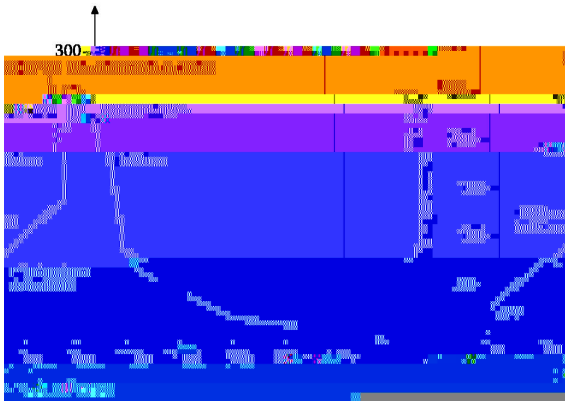
Reflow soldering



	Symbol	Min	Max	Unit
Preheat temperayure	T_s	150	200	
Preheat time	t_s	60	120	s
Ramp-up rate(T_l to T_p)			3	/s
Liquidus temperature	T_L	217		
Time above T_L	t_L	60	150	s
Peak temperature	T_p		260	
Time during which T_c is between (T_p-5) and T_p	t_p		30	s
Ramp-down rate(T_p to T_l)			6	/s

Note:

Wave soldering



Profile feature	
Average ramp-up rate	200 /s
Heating rate during preheat	1 /s to 2 /s typical;4 /s maximum
Final preheat temperature T_s	130
Preheat time (25 to T_s)	60s
Peak temperature T_p	260
Time within peak temperature t_p	10s
Ramp-down rate	5 /s maximum

